

Application No. 10/812,585

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

WHAT IS CLAIMED IS:

1. (CANCELLED)
2. (CANCELLED)
3. (CANCELLED)
4. (CANCELLED)
5. (CANCELLED)
6. (CANCELLED)
7. (CANCELLED)
8. (CANCELLED)
9. (CANCELLED)
10. (CANCELLED)
11. (CURRENTLY AMENDED) A method of reticulating a film

adhesive onto a perforated panel, said method including the steps of:

supporting the perforated panel;

adhering the film adhesive to the perforated panel without initiating a cure

of the film adhesive;

applying a vacuum to the film adhesive;

softening of the film adhesive;

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moving the perforated panel at a predetermined speed through a
reticulation unit, said reticulation unit having a contour head with a nozzle therein, said
perforated panel in contact with said contour head;

~~drying an airflow;~~

and

removing the film adhesive from the perforations by said airflow.

12. (ORIGINAL) The method of claim 11 wherein said step of
supporting prevents distortion of the panel.

13. (ORIGINAL) The method of claim 11 wherein said step of
adhering further includes the step of heating the film adhesive.

14. (PREVIOUSLY PRESENTED) The method of claim 13 further
including the step of using a radiant heat source for said heating at a temperature between
70° and 200° F for a predetermined amount of time.

15. (PREVIOUSLY PRESENTED) The method of claim 11 wherein said
step of applying a vacuum to said film adhesive creates a pressure of approximately 10 to
20 psi between the film adhesive and the panel thus allowing for initial adhesion.

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16. (ORIGINAL) The method of claim 11 further including the step of placing said airflow directly on the perforated panel.

17. (CANCELLED)

18. (ORIGINAL) The method of claim 11 further including the step of filtering said airflow.

19. (ORIGINAL) The method of claim 11 further including the step of heating said airflow.

20. (ORIGINAL) The method of claim 11 wherein said step of softening includes the step of containing heat near the film adhesive by a shroud and creating a greenhouse effect by said shroud.

21. (ORIGINAL) The method of claim 11 wherein said step of removing includes the step of controlling the rate of airflow such that the heated film adhesive is cut away from the perforations and forms a reticulated pattern.

22. (ORIGINAL) The method of claim 11 wherein said step of softening occurs prior to movement of the panel over said airflow.

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23. (CURRENTLY AMENDED) A method for panel and film adhesive reticulation, said method including the steps of:

- using a contoured surface to support the panel;
- applying pressure to the film adhesive and panel by a vacuum mechanism;
- heating the film adhesive until initial adhering of the film adhesive without curing;
- moving the panel, with initial film adhesion, through a reticulation unit, said reticulation unit including a contour head having a nozzle therein for directing an airflow and said reticulation unit having a shroud, the panel in contact with said contour head;
- softening the film adhesive with heat, said heat is contained within said shroud;
- drying said airflow;
- filtering said airflow;
- heating said airflow prior to entering said nozzle; and
- removing said film adhesive from perforations in of the panel with a predetermined rate of said airflow.

24. (CANCELLED)